PART NO. : HFJT1-1G01RL

FASTJACK™ (TABUP) WITH 1000BASE-T MAGNETICS
DESIGNED FOR IEEE802.3ab GIGABIT APPLICATIONS

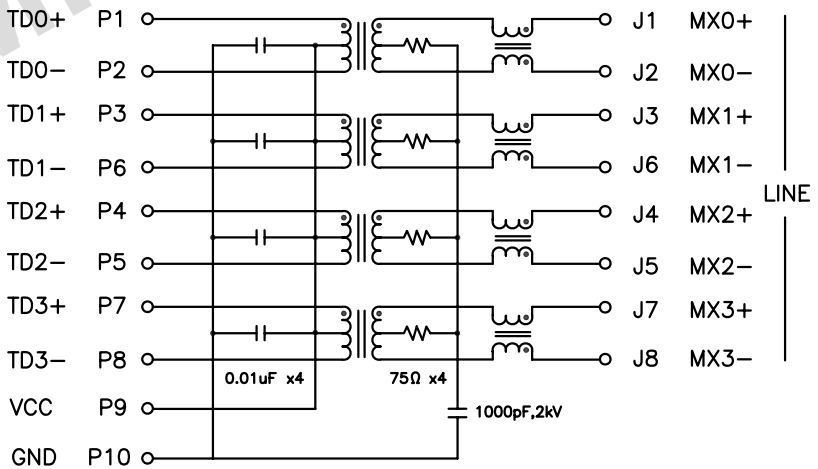
RoHS COMPLIANT

COMPATIBLE TO LEAD-FREE WAVE SOLDERING PROCESS FOR THROUGH HOLE COMPONENTS

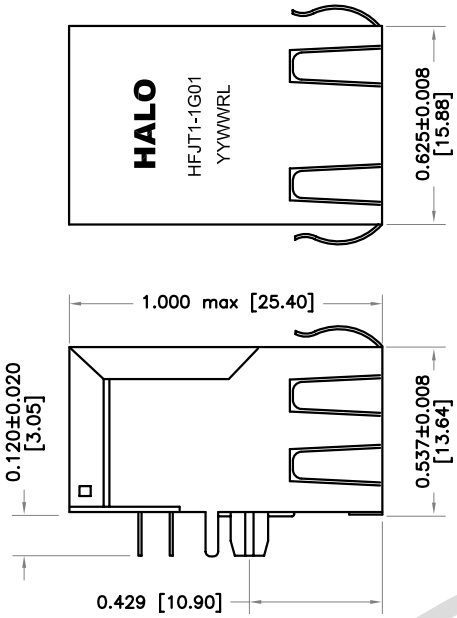
OPERATING TEMPERATURE 0/70°C

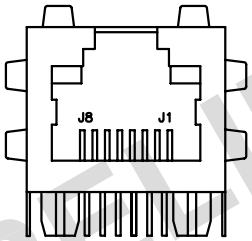
ELECTRICAL SPECIFICATIONS @ 25° C

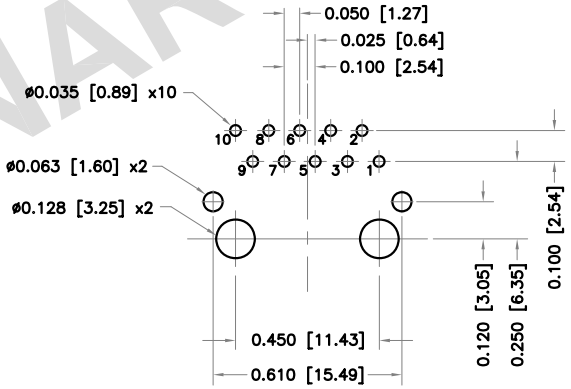
TURNS RATIO	1:1 ±3%
OCL (100KHz,0.1V,8mA)	350µH min
INSERTION LOSS	
1-100MHz	-1.1dB max
RETURN LOSS	
1-40MHz	-18dB min
60MHz	-14dB min
80MHz	-12dB min
100MHz	-10dB min
CROSSTALK 1-100MHz	-35dB typ
CMR 0.1-30MHz	-50dB typ
30-60MHz	-40dB typ
60-100MHz	-35dB typ
ISOLATION	1,500Vrms



HALO/PBL	TITLE	FastJack™ SINGLE	SIGNATURES		DATE	REV.	DESC.	DATE
	FOR	GIGABIT ETHERNET	DRAWN	LI ZHI ZHONG	4/15/11	A	FIRST ISSUE	4/15/11
	PART NO.	HFJT1-1G01RL	CHECKED	LEI KEONG	4/15/11			
	SCALE	NONE PAGE 1 OF 2	APPROVED	PETER LU	4/15/11			
CALIFORNIA, USA KOWLOON, HONG KONG SINGAPORE			FILE	HFJT1-1G01RL.DWG				







Housing Material: Polyester, Black UL94V–0
Contacts: Phosphor Bronze 30µin Au plating over Ni
Leads: Matte Sn over Ni
Shield: Cu Alloy with Ni plating 40µin min
Durability: 1000 mating cycles
Dimensions: Inch [mm]
Tolerances: ±0.008 inch if not specified

RECOMMENDED P.C. BOARD PATTERN (COMP. SIDE)

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	SCALE NONE	PAGE 2 OF 2	APPROVED PETER LU	4/15/11			
			FILE HFJT1–1G01RL.DWG				